

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.01284	100.0	0.26839
			<b>Subtotal</b>	<b>0.01284</b>	<b>100</b>	<b>0.26839</b>
Die	Doped silicon	Silicon (Si)	7440-21-3	0.15313	100.0	3.2
			<b>Subtotal</b>	<b>0.15313</b>	<b>100</b>	<b>3.2</b>
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.01479	10.0	0.309
	Silver alloy	Silver (Ag)	7440-22-4	0.00296	2.0	0.0618
	Lead alloy	Lead (Pb)	7439-92-1	0.13013	88.0	2.7192
			<b>Subtotal</b>	<b>0.14788</b>	<b>100</b>	<b>3.09</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.10275	100.0	2.14708
			<b>Subtotal</b>	<b>0.10275</b>	<b>100</b>	<b>2.14708</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.00703	0.03	0.14694
	Pure metal layer	Zinc (Zn)	7440-66-6	0.00469	0.02	0.09796
	Pure metal layer	Tin (Sn)	7440-31-5	0.00703	0.03	0.14694
	Pure metal layer	Iron (Fe)	7439-89-6	0.02578	0.11	0.53877
	Pure metal layer	Copper (Cu)	7440-50-8	23.39418	99.81	488.8594
			<b>Subtotal</b>	<b>23.43871</b>	<b>100</b>	<b>489.79001</b>
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.24726	100.0	5.167
			<b>Subtotal</b>	<b>0.24726</b>	<b>100</b>	<b>5.167</b>
Mould Compound	Polymer	Tetrabromobisphenol A/Epichlorohydrin polymer	40039-93-8	2.27692	3.0	47.58
	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	4.55385	6.0	95.16
	Polymer	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	7.58974	10.0	158.6
	Carbon Black	Carbon black	1333-86-4	0.37949	0.5	7.93
	Filler	Misc. Silica compounds (generic)	14808-60-7	59.19999	78.0	1237.08
	Flame retardant	Antimony Trioxide (Sb2O3) - cas no. 1309-64-4	1309-64-4	1.89744	2.5	39.65
			<b>Subtotal</b>	<b>75.89743</b>	<b>100</b>	<b>1586</b>
			<b>Total</b>	<b>100</b>	<b>100</b>	<b>2089.66248</b>

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